MAX3223 3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER WITH \pm 15-kV ESD PROTECTION

SLLS409K - JANUARY 2000 - REVISED MARCH 2004

- RS-232 Bus-Pin ESD Protection Exceeds ±15 kV Using Human-Body Model (HBM)
- Meets or Exceeds the Requirements of TIA/EIA-232-F and ITU v.28 Standards
- Operates With 3-V to 5.5-V V_{CC} Supply
- Operates Up To 250 kbit/s
- Two Drivers and Two Receivers
- Low Standby Current . . . 1 μA Typical
- External Capacitors . . . 4 × 0.1 μF
- Accepts 5-V Logic Input With 3.3-V Supply
- Alternative High-Speed Pin-Compatible Device (1 Mbit/s)
 - SNx5C3223
- Applications
 - Battery-Powered Systems, PDAs, Notebooks, Laptops, Palmtop PCs, and Hand-Held Equipment

DB, DW, OR PW PACKAGE (TOP VIEW) ĒΝ 20 FORCEOFF 19 V_{CC} C1+ 2 V+[] 3 18 **∏** GND C1−∏4 17 DOUT1 C2+∏5 16 RIN1 15 ROUT1 C2-[] 6 V-**∏** 7 14 | FORCEON 13 DIN1 DOUT2 1 8 RIN2 ¶ 9 12 DIN2 ROUT2 10 11 INVALID

description/ordering information

The MAX3223 consists of two line drivers, two line receivers, and a dual charge-pump circuit with ± 15 -kV ESD protection pin to pin (serial-port connection pins, including GND). The device meets the requirements of TIA/EIA-232-F and provides the electrical interface between an asynchronous communication controller and the serial-port connector. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. The device operates at data signaling rates up to 250 kbit/s and a maximum of 30-V/ μ s driver output slew rate.

ORDERING INFORMATION

TA	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	COIC (DW)	Tube of 25	MAX3223CDW	MAY2022
	SOIC (DW)	Reel of 2000	MAX3223CDWR	MAX3223C
000 to 7000	CCOD (DD)	Tube of 70	MAX3223CDB	MAGGGG
−0°C to 70°C	SSOP (DB)	Reel of 2000	MAX3223CDBR	MA3223C
	TSSOP (PW)	Tube of 70	MAX3223CPW	MA 00000
		Reel of 2000	MAX3223CPWR	MA3223C
	COIC (DW)	Tube of 25	MAX3223IDW	MAYAAAA
	SOIC (DW)	Reel of 2000	MAX3223IDWR	MAX3223I
-40°C to 85°C	CCOD (DD)	Tube of 70	MAX3223IDB	MDaggal
-40°C to 85°C	SSOP (DB)	Reel of 2000	MAX3223IDBR	MB3223I
	TCCOD (DWA)	Tube of 70	MAX3223IPW	MDaggal
	TSSOP (PW)	Reel of 2000	MAX3223IPWR	MB3223I

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER WITH ±15-kV ESD PROTECTION

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description/ordering information (continued)

Flexible control options for power management are available when the serial port is inactive. The auto-powerdown feature functions when FORCEON is low and FORCEOFF is high. During this mode of operation, if the device does not sense a valid RS-232 signal, the driver outputs are disabled. If FORCEOFF is set low and EN is high, both drivers and receivers are shut off, and the supply current is reduced to 1 μA. Disconnecting the serial port or turning off the peripheral drivers causes auto-powerdown to occur. Auto-powerdown can be disabled when FORCEON and FORCEOFF are high. With auto-powerdown enabled, the device is activated automatically when a valid signal is applied to any receiver input. The INVALID output is used to notify the user if an RS-232 signal is present at any receiver input. INVALID is high (valid data) if any receiver input voltage is greater than 2.7 V or less than -2.7 V, or has been between -0.3 V and 0.3 V for less than 30 μs. INVALID is low (invalid data) if the receiver input voltage is between -0.3 V and 0.3 V for more than 30 us. Refer to Figure 4 for receiver input levels.

Function Tables

EACH DRIVER

		INPUTS		OUTPUT	
DIN	FORCEON	FORCEOFF	VALID RIN RS-232 LEVEL	DOUT	DRIVER STATUS
Х	Χ	L	Х	Z	Powered off
L	Н	Н	Х	Н	Normal operation with
Н	Н	Н	X	L	auto-powerdown disabled
L	L	Н	Yes	Н	Normal operation with
Н	L	Н	Yes	L	auto-powerdown enabled
L	L	Н	No	Z	Powered off by
Н	L	Н	No	Z	auto-powerdown feature

H = high level, L = low level, X = irrelevant, Z = high impedance

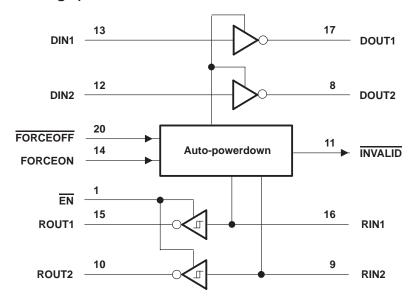
EACH RECEIVER

	INP	PUTS	OUTPUT
RIN	EN	VALID RIN RS-232 LEVEL	ROUT
L	L	Х	Н
Н	L	X	L
Х	Н	X	Z
Open	L	No	Н

H = high level, L = low level, X = irrelevant. Z = high impedance (off), Open = inputdisconnected or connected driver off



logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC} (see Note 1)	
Positive output supply voltage range, V+ (see Note 1)	0.3 V to 7 V
Negative output supply voltage range, V– (see Note 1)	0.3 V to –7 V
Supply voltage difference, V+ – V– (see Note 1)	13 V
Input voltage range, V _I : Driver, FORCEOFF, FORCEON, EN	0.3 V to 6 V
Receiver	–25 V to 25 V
Output voltage range, VO: Driver	13.2 V to 13.2 V
Receiver, INVALID	\dots -0.3 V to V _{CC} + 0.3 V
Package thermal impedance, θ _{JA} (see Notes 2 and 3): DB package	70°C/W
DW package	58°C/W
PW package	83°C/W
Operating virtual junction temperature, T _J	150°C
Storage temperature range, T _{stq}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltages are with respect to network GND.
 - 2. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.



MAX3223

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recommended operating conditions (see Note 4 and Figure 6)

				MIN	NOM	MAX	UNIT
	Supply voltage		V _{CC} = 3.3 V	3	3.3	3.6	V
			V _{CC} = 5 V	4.5	5	5.5	V
V	Driver and control high level input voltage	DIN, EN, FORCEOFF,	$V_{CC} = 3.3 \text{ V}$	2			V
VIH	Driver and control high-level input voltage	FORCEON	V _{CC} = 5 V	2.4			V
V_{IL}	Driver and control low-level input voltage	DIN, EN, FORCEOFF, FORCE	ON			0.8	V
17.	Driver and control input voltage	DIN, EN, FORCEOFF, FORCE	ON	0		5.5	V
VI Receiver input voltage			-25		25	V	
т.	T _Δ Operating free-air temperature		MAX3223C	0		70	°C
TA	Operating nee-air temperature		MAX3223I	-40		85	C

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 $V \pm 0.3$ V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 $V \pm 0.5$ V.

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAME	TER	TES	T CONDITIONS	MIN	TYP†	MAX	UNIT
II	Input leakage current	EN, FORCEOFF, FORCEON				±0.01	±1	μΑ
		Auto-powerdown disabled		No load, FORCEOFF and FORCEON at V _{CC}		0.3	1	mA
ICC	Supply current	Powered off	$V_{CC} = 3.3 \text{ V or 5 V},$ $T_{A} = 25^{\circ}\text{C}$	No load, FORCEOFF at GND		1	10	
		Auto-powerdown enabled	14 - 20 0	No load, FORCEOFF at V _{CC} , FORCEON at GND, All RIN are open or grounded		1	10	μΑ

† All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C. NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V \pm 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.



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DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER	TES	T CONDITIONS	MIN	TYP†	MAX	UNIT
Vон	High-level output voltage	DOUT at $R_L = 3 \text{ k}\Omega$ to GN	D	5	5.4		V
VOL	Low-level output voltage	DOUT at $R_L = 3 \text{ k}\Omega$ to GN	DOUT at R _L = $3 \text{ k}\Omega$ to GND		-5.4		٧
lн	High-level input current	VI = VCC			±0.01	±1	μΑ
Ι _Ι L	Low-level input current	V _I at GND			±0.01	±1	μΑ
	Object since it and and account t	V _{CC} = 3.6 V,	VO = 0 V		±35	±60	A
los	Short-circuit output current‡	V _{CC} = 5.5 V,	VO = 0 V		±35	±60	mA
r _O	Output resistance	V_{CC} , V+, and V- = 0 V,	$V_O = \pm 2 V$	300	10M		Ω
	Outrout lealings assument	FORCEOFF = GND	$V_O = \pm 12 \text{ V}, V_{CC} = 3 \text{ V to } 3.6 \text{ V}$			±25	^
loff	Output leakage current	FORCEOFF = GND	$V_O = \pm 10 \text{ V}, V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$			±25	μΑ

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER	TEST CONDITIONS MIN TYP [†] MAX				MAX	UNIT
	Maximum data rate	C _L = 1000 pF, One DOUT switching,	$R_L = 3 kΩ$, See Figure 1	250			kbit/s
t _{sk(p)}	Pulse skew§	C _L = 150 pF to 2500 pF, See Figure 2	$R_L = 3 \text{ k}\Omega \text{ to } 7 \text{ k}\Omega,$		100		ns
SR(tr)	Slew rate, transition region	V _{CC} = 3.3 V,	C _L = 150 pF to 1000 pF	6		30	\//uo
SK(II)	(See Figure 1)	$V_{CC} = 3.3 \text{ V},$ $R_L = 3 \text{ k}\Omega \text{ to 7 k}\Omega$	C _L = 150 pF to 2500 pF	4		30	V/μs

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.



^{\$}Short-circuit durations should be controlled to prevent exceeding the device absolute power-dissipation ratings, and not more than one output should be shorted at a time.

[§] Pulse skew is defined as |tpLH - tpHL| of each channel of the same device.

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RECEIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Vон	High-level output voltage	$I_{OH} = -1 \text{ mA}$	V _{CC} -0.6	V _{CC} -0.1		V
VOL	Low-level output voltage	I _{OL} = 1.6 mA			0.4	V
\/-	Decisive weign inner the weekeld value	V _{CC} = 3.3 V		1.6	2.4	V
V _{IT+}	Positive-going input threshold voltage	V _{CC} = 5 V		1.9	2.4	٧
\/_	No notive point input through old valte as	V _{CC} = 3.3 V	0.6	1.1		.,
V _{IT} –	Negative-going input threshold voltage	V _{CC} = 5 V	0.8	1.4		٧
V _{hys}	Input hysteresis (V _{IT+} - V _{IT-})			0.5		V
l _{off}	Output leakage current	EN = V _{CC}		±0.05	±10	μΑ
rį	Input resistance	$V_I = \pm 3 \text{ V to } \pm 25 \text{ V}$	3	5	7	kΩ

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}C$.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V \pm 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4)

PARAMETER		TEST C	TEST CONDITIONS		XAN	UNIT
tPLH	Propagation delay time, low- to high-level output	C _L = 150 pF,	See Figure 3	150		ns
tPHL	Propagation delay time, high- to low-level output	C _L = 150 pF,	See Figure 3	150		ns
ten	Output enable time	C _L = 150 pF, See Figure 4	$R_L = 3 \text{ k}\Omega$,	200		ns
t _{dis}	Output disable time	C _L = 150 pF, See Figure 4	$R_L = 3 \text{ k}\Omega$,	200		ns
t _{sk(p)}	Pulse skew [‡]	See Figure 3		50		ns

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V \pm 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.



[‡] Pulse skew is defined as |tpLH - tpHL| of each channel of the same device.

AUTO-POWERDOWN SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

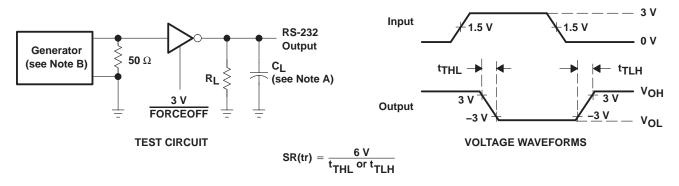
PARAMETER TEST		TEST C	ONDITIONS	MIN	MAX	UNIT
V _{T+(valid)}	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND,	FORCEOFF = V _{CC}		2.7	٧
V _T –(valid)	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND,	FORCEOFF = V _{CC}	-2.7		٧
VT(invalid)	Receiver input threshold for INVALID low-level output voltage	FORCEON = GND,	FORCEOFF = V _{CC}	-0.3	0.3	٧
VOH	INVALID high-level output voltage	$\frac{I_{OH} = -1 \text{ mA}}{FORCEOFF} = V_{CC}$	FORCEON = GND,	V _{CC} -0.6		٧
VOL	INVALID low-level output voltage	I _{OL} = 1.6 mA, FORCEOFF = V _{CC}	FORCEON = GND,		0.4	V

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

	PARAMETER	TYP	UNIT
tvalid	Propagation delay time, low- to high-level output	1	μs
^t invalid	Propagation delay time, high- to low-level output	30	μs
ten	Supply enable time	100	μs

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

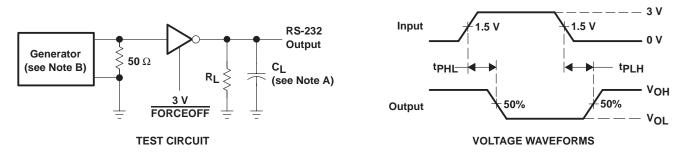
B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50~\Omega$, 50% duty cycle, $t_\Gamma \le 10$ ns. $t_f \le 10$ ns.

Figure 1. Driver Slew Rate

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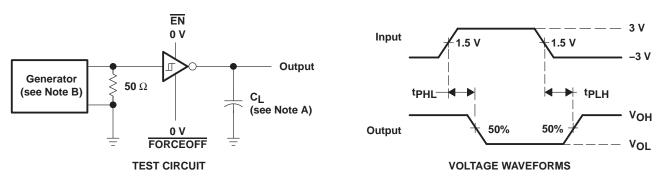
PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_r \le 10$ ns. $t_f \le 10$ ns.

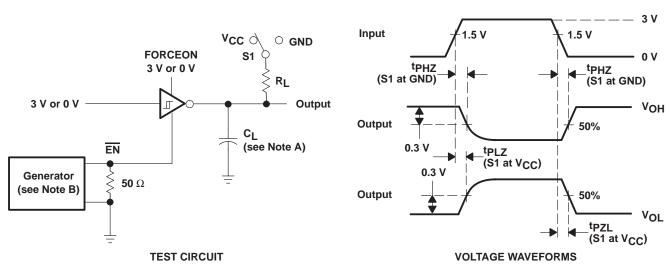
Figure 2. Driver Pulse Skew



NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: $Z_O = 50~\Omega$, 50% duty cycle, $t_f \le 10~\text{ns}$.

Figure 3. Receiver Propagation Delay Times



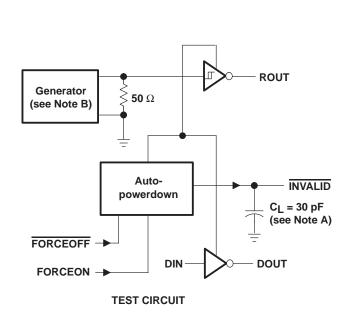
NOTES: A. C_I includes probe and jig capacitance.

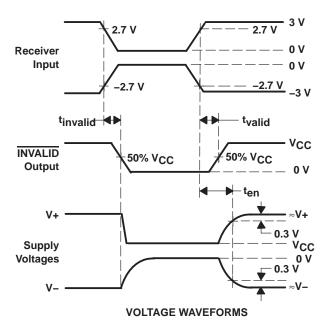
B. The pulse generator has the following characteristics: $Z_O = 50 \Omega$, 50% duty cycle, $t_f \le 10$ ns. $t_f \le 10$ ns.

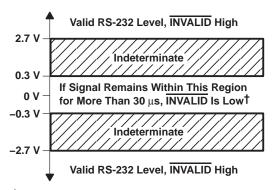
Figure 4. Receiver Enable and Disable Times



PARAMETER MEASUREMENT INFORMATION







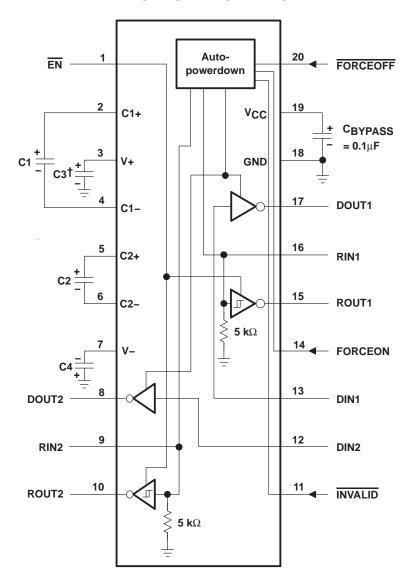
 † Auto-powerdown disables drivers and reduces supply current to 1 μ A.

NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 5 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_f \le 10$ ns. $t_f \le 10$ ns.

Figure 5. INVALID Propagation Delay Times and Supply Enabling Time

APPLICATION INFORMATION



†C3 can be connected to VCC or GND.

NOTES: A. Resistor values shown are nominal.

B. Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they should be connected as shown.

V_{CC} vs CAPACITOR VALUES

VCC	C1	C2, C3, C4
$\begin{array}{c} \textbf{3.3 V} \pm \textbf{0.3 V} \\ \textbf{5 V} \pm \textbf{0.5 V} \\ \textbf{3 V to 5.5 V} \end{array}$	0.1 μF 0.047 μF 0.1 μF	0.1 μF 0.33 μF 0.47 μF

Figure 6. Typical Operating Circuit and Capacitor Values









PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
MAX3223CDB	ACTIVE	SSOP	DB	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223CDBE4	ACTIVE	SSOP	DB	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223CDBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223CDBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223CDW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223CDWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223CDWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223CPW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223CPWE4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223CPWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223CPWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223IDB	ACTIVE	SSOP	DB	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223IDBE4	ACTIVE	SSOP	DB	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223IDBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223IDBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223IDW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223IDWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223IDWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223IDWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223IPW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223IPWE4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223IPWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3223IPWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs. **LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.



PACKAGE OPTION ADDENDUM

5-Sep-2005

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

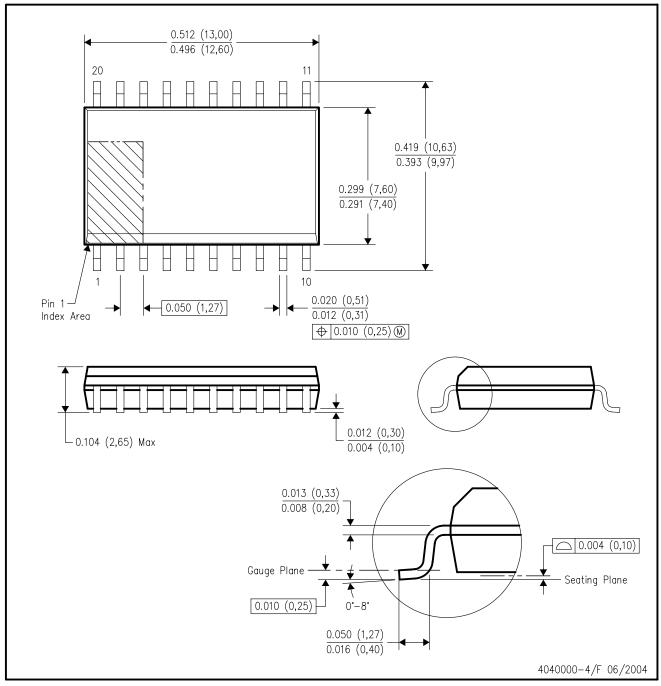
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

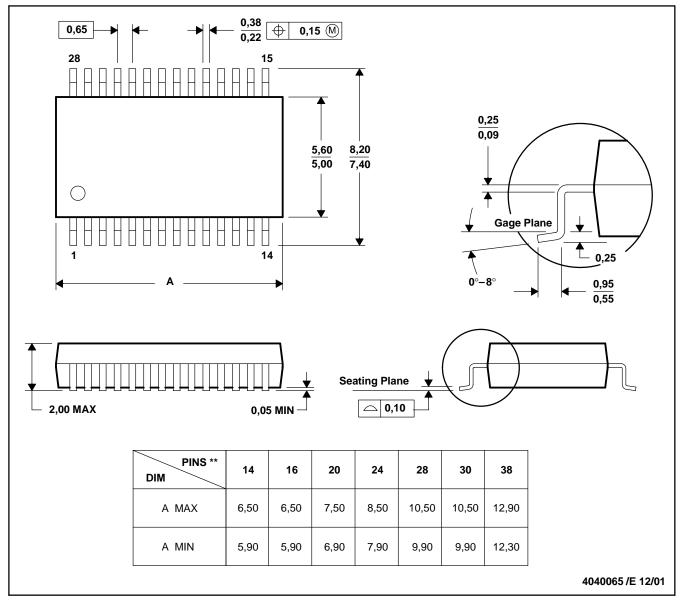
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

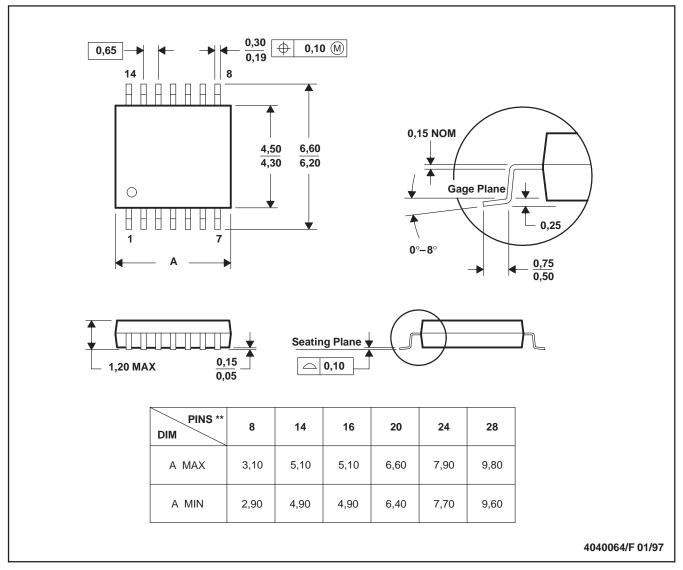
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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